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Field Device Integration (FDI) - Part 7: FDI Communication Devices

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

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EUROPEAN STANDARD
NORME EUROPÉENNE
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English Version

**Field Device Integration (FDI) - Part 7: FDI Communication
Devices
(IEC 62769-7:2015)**

Intégration des appareils de terrain (FDI) - Partie 7:
Appareils de communication FDI
(IEC 62769-7:2015)

Feldgeräteintegration (FDI) - Teil 7: Kommunikationsgeräte
(IEC 62769-7:2015)

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European foreword

The text of document 65E/350/CDV, future edition 1 of IEC 62769-7, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62769-7:2015.

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Annex ZA (normative)

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NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804-3	-	Function Blocks (FB) for process control -- Part 3: Electronic Device Description Language (EDDL)	EN 61804-3	-
IEC 61804-4	-	Function blocks (FB) for process control -- - Part 4: EDD interpretation	-	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN 62541-4	-
IEC 62541-6	-	OPC unified architecture - Part 6: Mappings	EN 62541-6	-
IEC 62541-7	-	OPC unified architecture - Part 7: Profiles	EN 62541-7	-
IEC 62541	series	OPC Unified Architecture	EN 62541	series
IEC 62541-100	-	OPC unified architecture - Part 100: Device Interface	EN 62541-100	-
IEC 62769-1	-	Devices and integration in enterprise systems; Field Device Integration - Part 1: Overview	-	-
IEC 62769-2	-	Devices and integration in enterprise systems; Field Device Integration - Part 2: FDI Client	-	-
IEC 62769-3	-	Devices and integration in enterprise systems; Field Device Integration - Part 3: FDI Server	-	-
IEC 62769-4	2015	Devices and integration in enterprise systems; Field Device Integration - Part 4: FDI Packages	-	-
IEC 62769-5	-	Devices and integration in enterprise systems; Field Device Integration - Part 5: FDI Information Model	-	-
IEC/TR 62541-1	-	OPC unified architecture - Part 1: Overview and concepts	CLC/TR 62541-1	-



INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI) –
Part 7: FDI Communication Devices**

**Intégration des appareils de terrain (FDI) –
Partie 7: Appareils de communication FDI**





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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field Device Integration (FDI) –
Part 7: FDI Communication Devices**

**Intégration des appareils de terrain (FDI) –
Partie 7: Appareils de communication FDI**

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FIELD DEVICE INTEGRATION (FDI) –

Part 7: FDI Communication Devices

FOREWORD

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International Standard IEC 62769-7 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

CDV	Report on voting
65E/350/CDV	65E/420/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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- a) Method for the Supplying and Installation of Device-Specific Functionalities, see Patent Family DE10357276;
- b) Method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) Methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
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FIELD DEVICE INTEGRATION (FDI) –

Part 7: FDI Communication Devices

1 Scope

This part of IEC 62769 specifies the elements implementing communication capabilities called Communication Devices (IEC 62769-5).

The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration. The document scope with respect to FDI Packages is limited to Communication Devices. The Communication Server shown in Figure 1 is an example of a specific Communication Device.

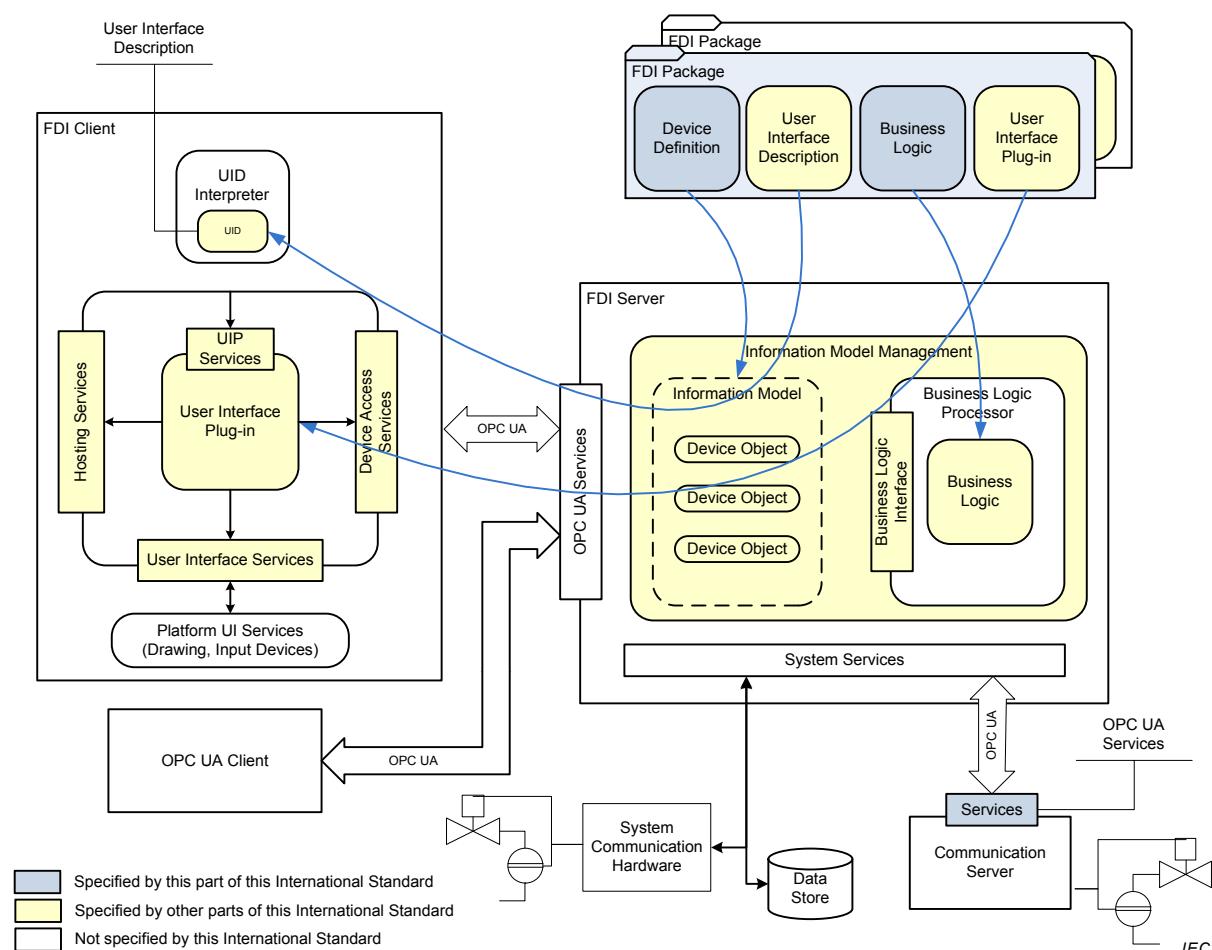


Figure 1 – FDI architecture diagram

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804-3, *Function blocks (FB) for process control and Electronic Device Description Language (EDDL) – Part 3: EDDL syntax and semantics*

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IEC 62541-7, *OPC Unified Architecture – Part 7: Profiles*

IEC 62541-100, *OPC Unified Architecture – Part 100: OPC UA for Devices*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

NOTE IEC 62769-1 is technically identical to FDI-2021.

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

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IEC 62769-3, *Field Device Integration (FDI) – Part 3: FDI Server*

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IEC 62769-4:2015, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

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